

Features

- N-Channel, 3.3V Logic Level Control
- Enhancement mode
- Very low on-resistance $R_{DS(on)}$ @ $V_{GS}=3.3$ V
- Fast Switching
- 100% Avalanche Tested
- Pb-free lead plating; RoHS compliant

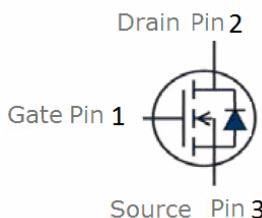
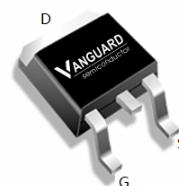


Halogen-Free

Part ID	Package Type	Marking	Tape and reel information
VSD005N05LS	TO-252	005N05L	2500pcs/Reel

V_{DS}	50	V
$R_{DS(on),TYP} @ V_{GS}=5V$	4.5	mΩ
$R_{DS(on),TYP} @ V_{GS}=3.3V$	4.9	mΩ
I_D	80	A

TO-252



Maximum ratings, at $T_j=25$ °C, unless otherwise specified

Symbol	Parameter	Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage	50	V
I_s	Diode continuous forward current	$T_c = 25^\circ\text{C}$	A
I_D	Continuous drain current@ $V_{GS}=5V$	$T_c = 25^\circ\text{C}$	A
		$T_A = 100^\circ\text{C}$	A
I_{DM}	Pulse drain current tested ①	$T_c = 25^\circ\text{C}$	A
I_{AS}	Avalanche current	$L=0.3\text{mH}$	A
E_{AS}	Avalanche energy, single pulsed ②	135	mJ
P_D	Maximum power dissipation	$T_A = 25^\circ\text{C}$	W
V_{GS}	Gate-Source voltage	±12	V
$T_{STG} T_J$	Storage and operating temperature range	-55 to 175	°C

Thermal Characteristics

Symbol	Parameter	Typical	Unit
$R_{\theta JC}$	Thermal Resistance-Junction to Case	1.8	°C/W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	48	°C/W

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ $T_c = 25^\circ\text{C}$ (unless otherwise stated)						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ $I_D=250\mu\text{A}$	50	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current($T_c=25^\circ\text{C}$)	$V_{\text{DS}}=50\text{V}, V_{\text{GS}}=0\text{V}$	--	--	1	μA
	Zero Gate Voltage Drain Current($T_c=125^\circ\text{C}$)	$V_{\text{DS}}=50\text{V}, V_{\text{GS}}=0\text{V}$	--	--	100	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 12\text{V}, V_{\text{DS}}=0\text{V}$	--	--	± 100	nA
$V_{\text{GS(TH)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_D=250\mu\text{A}$	0.5	1.0	1.5	V
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance ^③	$V_{\text{GS}}=5\text{V}, I_D=30\text{A}$	--	4.5	5.0	$\text{m}\Omega$
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance ^③	$V_{\text{GS}}=4.5\text{V}, I_D=20\text{A}$	--	4.7	6.0	$\text{m}\Omega$
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance ^③	$V_{\text{GS}}=3.3\text{V}, I_D=5\text{A}$	--	4.9	8.0	$\text{m}\Omega$
Dynamic Electrical Characteristics @ $T_c = 25^\circ\text{C}$ (unless otherwise stated)						
C_{iss}	Input Capacitance	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	--	7820	--	pF
C_{oss}	Output Capacitance		--	285	--	pF
C_{rss}	Reverse Transfer Capacitance		--	175	--	pF
Q_g	Total Gate Charge	$V_{\text{DS}}=25\text{V}, I_D=10\text{A}, V_{\text{GS}}=5\text{V}$	--	47	--	nC
Q_{gs}	Gate-Source Charge		--	11	--	nC
Q_{gd}	Gate-Drain Charge		--	14	--	nC
Switching Characteristics						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=20\text{V}, I_D=10\text{A}, R_{\text{G}}=3.5\Omega, V_{\text{GS}}=5\text{V}$	--	10	--	nS
t_r	Turn-on Rise Time		--	21	--	nS
$t_{\text{d(off)}}$	Turn-Off Delay Time		--	45	--	nS
t_f	Turn-Off Fall Time		--	25	--	nS
Source- Drain Diode Characteristics@ $T_c = 25^\circ\text{C}$ (unless otherwise stated)						
V_{SD}	Forward on voltage	$I_{\text{SD}}=30\text{A}, V_{\text{GS}}=0\text{V}$	--	0.80	1.2	V
t_{rr}	Reverse Recovery Time	$T_j=25^\circ\text{C}, I_{\text{SD}}=20\text{A}, \frac{di}{dt}=500\text{A}/\mu\text{s}$	--	36	--	nS
Q_{rr}	Reverse Recovery Charge		--	41	--	nC

NOTE:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Limited by $T_{j\text{max}}$, starting $T_j = 25^\circ\text{C}$, $L = 0.3\text{mH}$, $R_G = 25\Omega$, $I_{AS} = 30\text{A}$, $V_{GS} = 5\text{V}$. Part not recommended for use above this value
- ③ Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.

Typical Characteristics

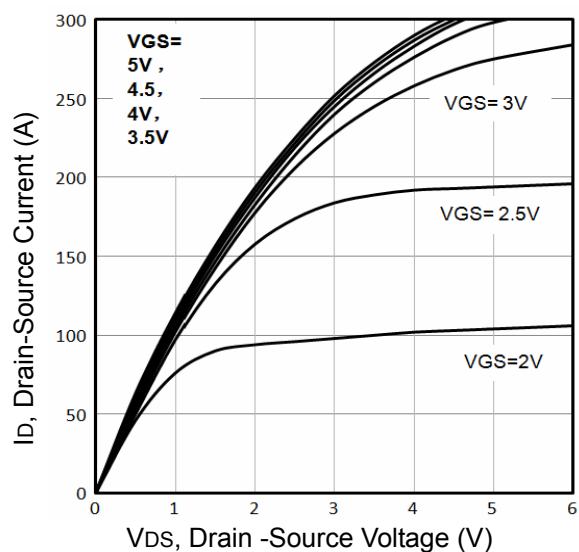


Fig1. Typical Output Characteristics

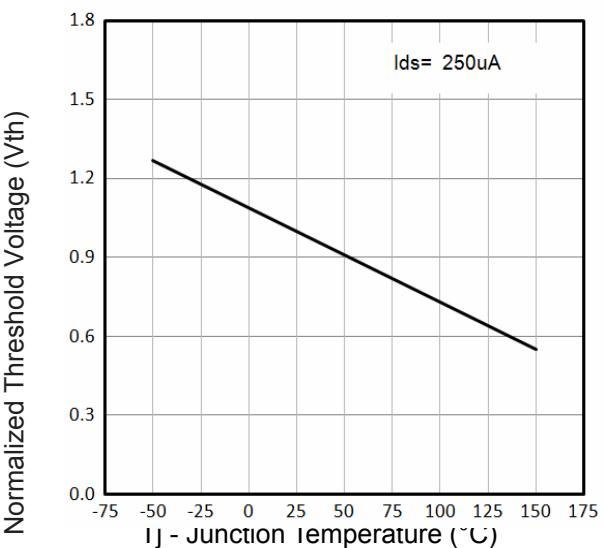


Fig2. Normalized Threshold Voltage Vs. Temperature

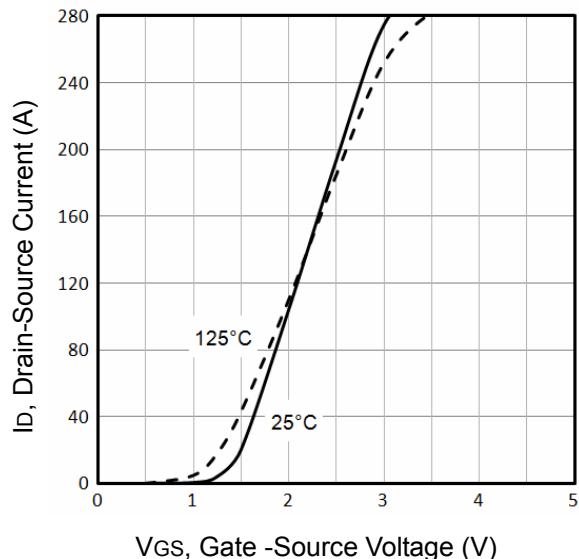


Fig3. Typical Transfer Characteristics

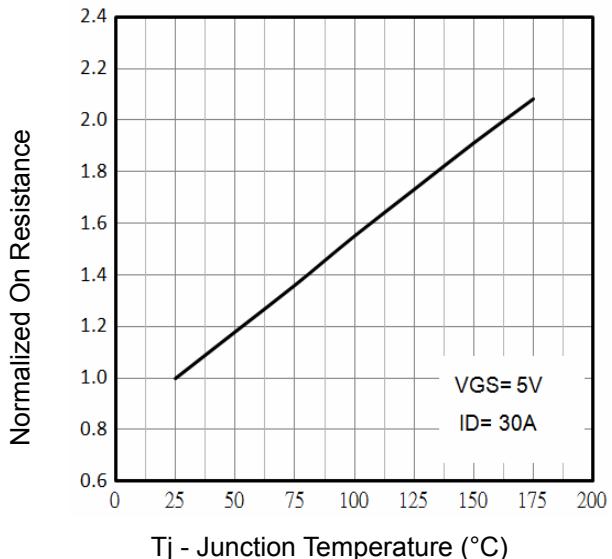


Fig4. Normalized On-Resistance Vs. Temperature

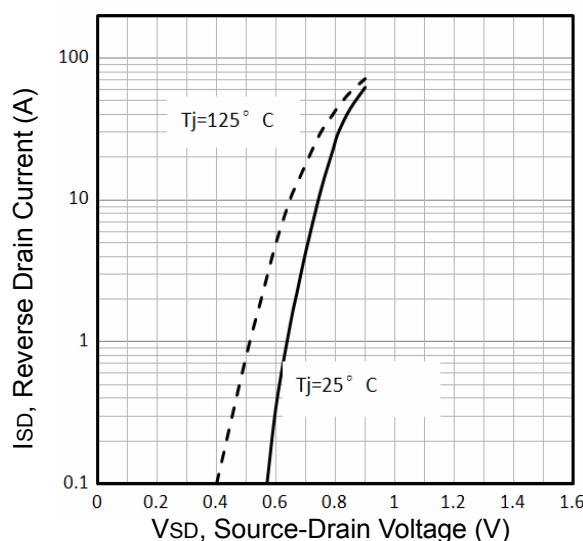


Fig5. Typical Source-Drain Diode Forward Voltage

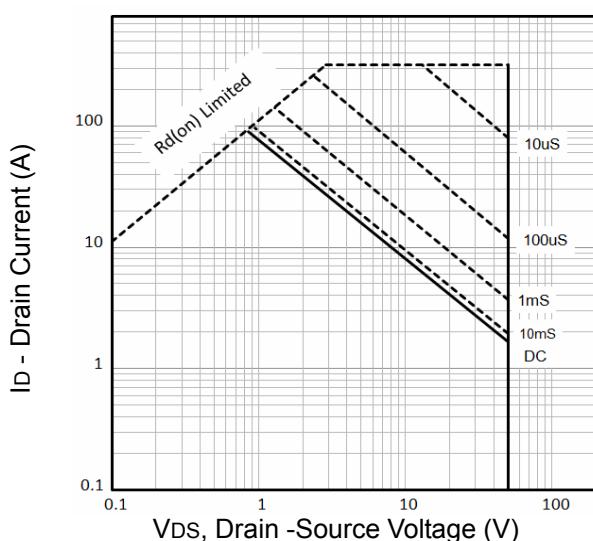


Fig6. Maximum Safe Operating Area

Typical Characteristics

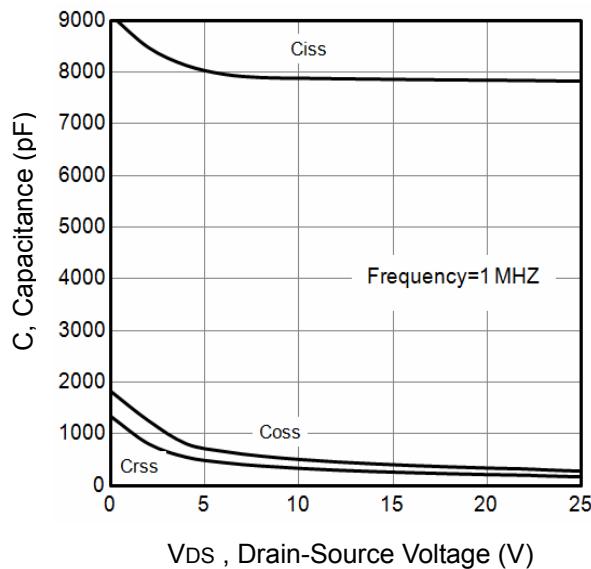


Fig7. Typical Capacitance Vs.Drain-Source Voltage

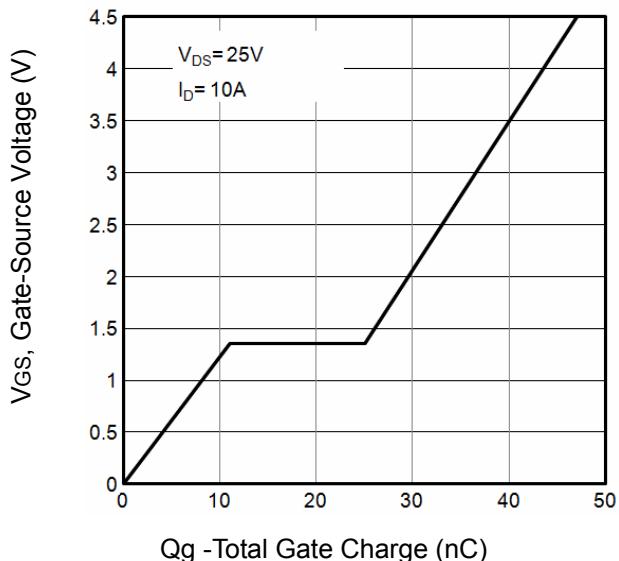


Fig8. Typical Gate Charge Vs.Gate-Source

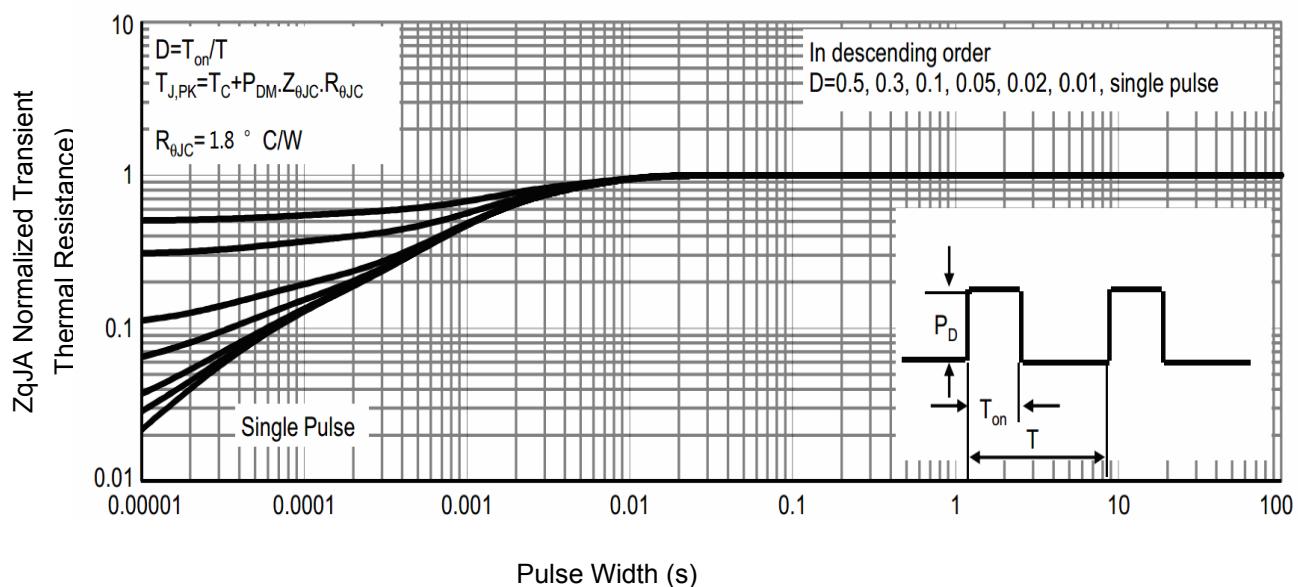


Fig9 . Normalized Maximum Transient Thermal Impedance

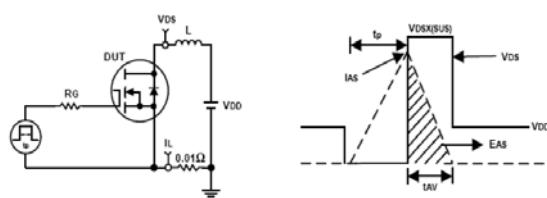


Fig10. Unclamped Inductive Test Circuit and waveforms

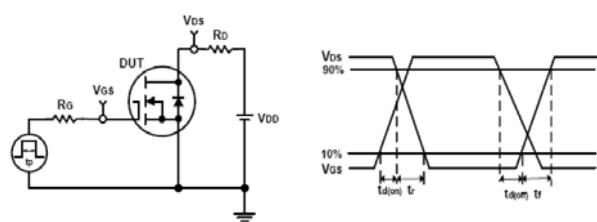
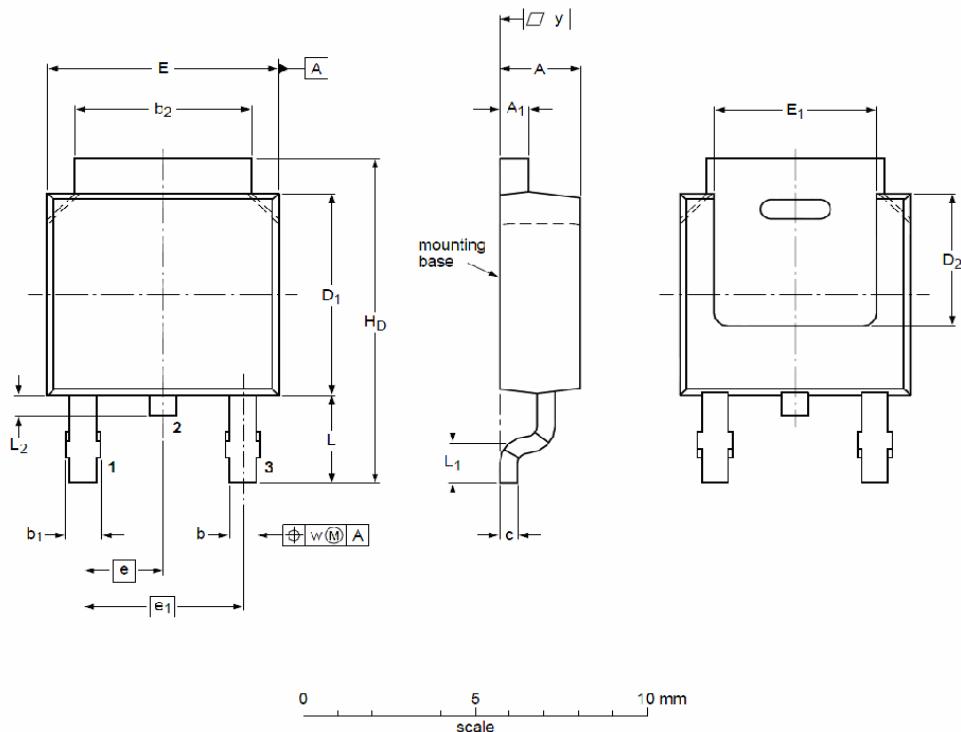


Fig11. Switching Time Test Circuit and waveforms

TO-252 Package Outline



DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	2.22	2.30	2.38	A ₁	0.46	0.58	0.93
b	0.71	0.79	0.89	b ₁	0.90	0.98	1.10
b ₂	5.00	5.30	5.46	c	0.20	0.40	0.56
D ₁	5.98	6.05	6.22	D ₂	--	4.00	--
E	6.47	6.60	6.73	E ₁	5.10	5.28	5.45
e	--	2.28	--	e ₁	--	4.57	--
H _D	9.60	10.08	10.40	L	2.75	2.95	3.05
L ₁	--	0.50	--	L ₂	0.80	0.90	1.10
w	--	0.20	--	y	0.20	--	--

Customer Service

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